TOPICAL AREAS:

DESIGN ENGINEERING

- · CAD/CAE/FEM
- · Multi-body Dynamics
- Mechatronics
- Vibrations
- · Biomechanics
- Automotive Engineering
- Aerospace Engineering
- · Hybrid Vehicle Technology
- Vehicle Dynamics

ENERGY ENGINEERING

- Fluid Mechanics/CFD
- · Combustion and IC Engines
- Solar Thermal Energy
- · Bio Energy
- · Energy Management
- · Energy Conversion
- · Renewable Energy
- · Smart Energy Materials
- · Photovoltaic and Fuel Cells

- · Biomedical Engineering
- · Artificial Intelligence
- Electronic Materials and Devices

MULTI DISCIPLINARY ENGINEERING

- · Robotics and Automation
- · Computer Networks and
- Communication
- Bioinformatics
- Nanotechnology
- · Power and Energy Systems
- · Cybersecurity and Privacy
- Environmental Engineering

ENGINEERING MATERIALS

- Composites Materials
- Biomaterials
- · Polymers and Biopolymers
- Sustainable Construction Materials
- Nano Materials
- · Organic and Inorganic Chemistry
- Applied Chemistry
- Coatings
- Metals, Allovs and Ceramics

MANUFACTURING ENGINEERING

- · Additive Manufacturing
- Rapid Prototyping
- · Conventional/ Non-conventional Machining
- · Green Manufacturing
- · Joining Technologies
- Laser Machining Technology
- · Metal-Forming Technologies
- · Smart Manufacturing

INDUSTRIAL ENGINEERING

- · Artificial Intelligence in Production
 - · Flexible Manufacturing Systems
 - Industry 4.0 and 5.0 in Production
 - · Automation and Robotics
 - · Lean Manufacturing
 - · Reliability & Maintenance Engineering
 - Supply Chain Management
 - · Work Design and Ergonomics
 - · Information Management
 - · Communication Systems

- · Augmented Reality and Virtual Reality

CALL FOR PAPERS

Academicians, researchers and industry people are being invited to submit their original research papers previously unpublished, not currently under review by another conference or journal. All submissions will be subjected to at least two blind reviews. Acceptance will be based entirely on quality, relevance and originality. The authors can send their Abstracts/ Full paper(s) online. The Template for submission is provided at the conference website:

Submit your Abstracts/ Full paper(s) through the website link:

https://conference.manipal.edu/RAiSE-2023/

The decision of oral presentation will be strictly followed as per approval of technical review committee. All selected peer-reviewed research/ review papers presented in the conference will be recommended for publication in our supporting publishing partners.

IMPORTANT DATES

Abstract submission deadline	30th June 2023	
Full paper submission deadline	30th July 2023	
Notification of Acceptance	15th August 2023	
Last date of Registration & Payment	15th September 2023	
Last date for Revised Paper Submission	15th September 2023	
Conference Dates	4th & 5th October 2023	

REGISTRATION FEE

DELEGATE CATEGORY	INR	USD
UG/PG/Research Scholar (Virtual)	5000	100
UG/PG/Research Scholar (Offline)*	8000	120
Early Bird (Registration Deadline: 31st Aug	ust 2023)	
Academia/Industry (Virtual)	8000	120
Academia/Industry (Offline)*	12000	150
Regular Registration (Registration Deadline: 15th September 2023)		
Academia/Industry (Virtual)	10000	150
Academia/Industry (Offline)*	15000	200
Attendee (Accompany Delegates)	5000	100

- · Registration fee includes SCOPUS Engineering Proceedings
- Includes Certificate to presenting author
- Registration fee does not include journal publication charges
- *The registration fee includes entry to all sessions, tea/snacks, and lunch
- *The registration fee includes Conference Kit
- *GALA dinner (Dhow Cruise)

AWARDS

YOUNG RESEARCHER **AWARD**

Three awards - To young researchers below the age of 35 years for exemplary research presented at the conference (3 Awards).

BEST PAPER AWARD

One award per session - To recognise and promote quality contributions to scientific research community.

SUPPORTING PUBLISHING PARTNERS

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Mode: Hybrid

Organized by:

Department of Mechanical and Industrial Engineering Manipal Institute of Technology, MAHE, Manipal, India School of Engineering and IT

MAHE, Dubai

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Manipal Academy of Higher Education (MAHE), an Institution of Eminence Deemed to be University, is a self-financing higher educational institution that started its operations in 1953.MAHE offers world-class facilities and pedagogy, which are constantly reviewed and upgraded to reflect the latest trends and developments in higher education.MAHE is an ISO 9001:2015, 14001:2015, and 50001:2018 certified Deemed University and has won the prestigious IMC Ramakrishna Baiai National Quality Award and the International Asia Pacific Quality Award. Over 35,000 students from 60+ nations live, learn, and play in the sprawling University town, nestled on a plateau in Karnataka's Udupi district. MAHE is declared as Institution of Eminence Deemed to be University (IoE) by the Ministry of Education, Govt. of India. The Manipal Group, a pioneer in higher education services with more than six decades of experience in excellence, operates campuses in Sikkim, Jaipur, Bengaluru in India, Dubai, Malaysia, and Antigua, in the Caribbean.

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ABOUT THE DEPARTMENT OF MECHANICAL & INDUSTRIAL ENGINEERING

The Department of Mechanical and Industrial Engineering (MIE), started in the year 1960is the largest in the Institute comprising 2 undergraduate and 4 postgraduate programs. The department's strength lies in having a good number of experienced and wellqualified faculty and state-of-the-art infrastructural facilities. Innovative teaching methods are followed to impart quality education to the students. Department is recognized as Quality Improvement Program (QIP) minor Centre by MHRD, Govt of India, which has given a boost to the research activities in the department.

ABOUT CONFERENCE

The International Conference RAiSE-2023 focuses on integrating multidisciplinary domains and aims to cover the latest developments in technology, including applications in fields of mechanical sciences. computer science, electronics, applied sciences and their interdisciplinary domains. The conference is aimed at providing a common platform for academicians, industrialists, research scholars, and students to exchange their expertise and knowledge, broaden their technical knowledge, and deepen their understanding of cutting-edge research.

OBJECTIVES OF CONFERENCE

RAiSE-2023 targets active researchers and experts from various disciplines to have the opportunity to introduce their new findings and collaborate with interdisciplinary research fields. The conference will provide a forum for in-depth technical discussions and the exchange of research ideas on a wide range of topics, offering insights into potential applications in industry and society. Additionally, young researchers will be exposed to recent advances in the fields of science and engineering, including areas with significant mathematical, scientific, and computational prominence. Overall, the conference aims to promote collaboration and knowledge-sharing among experts and researchers to advance the field of multi-disciplinary sciences and engineering.

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